Dexerials

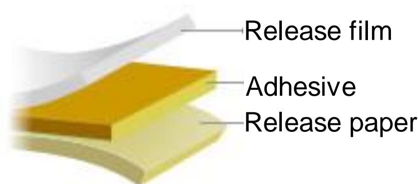
Technical Data Sheet

Thermosetting tapes for FPC D3410 series

Features

- ■ Excellent bonding strength for glass epoxy or polyimide film.
- ■ Short-time curing with low temperature shortens processing time.
- ■ It is possible to store at room temperature.
- ■ Initial tack enables tentative positioning.
- ■ Suitable processes are multilayer press or vacuum quick press and postcure.

Structure



Product name	D3410	D3411
Main component	NBR/Epoxy	NBR/Epoxy
Carrier	Non-carrier	Non-carrier
Color	Light yellow	Light yellow
Adhesive thickness (μm)	About 35	About 25
Release film thickness (μm)	About 38	About 38
Release paper thickness (μm)	About 115	About 115
Bonding strength (N/20mm) *	20	14
St'd size (width & length)	500mm×100m	500mm×100m

* 90° peeling strength(substrate :CCL/PI)

＜Standard bonding condition＞

■Vacuum quick press and pos cure process
Press temperature：130℃ to 160℃
Press time：1 to 2min
Pressure：1.5 to 2.0MPa
Postcure condition：140℃ 60min

■Long press process
Press temperature：160℃
Press time：60min
Pressure：2 to 3MPa

Suitable use

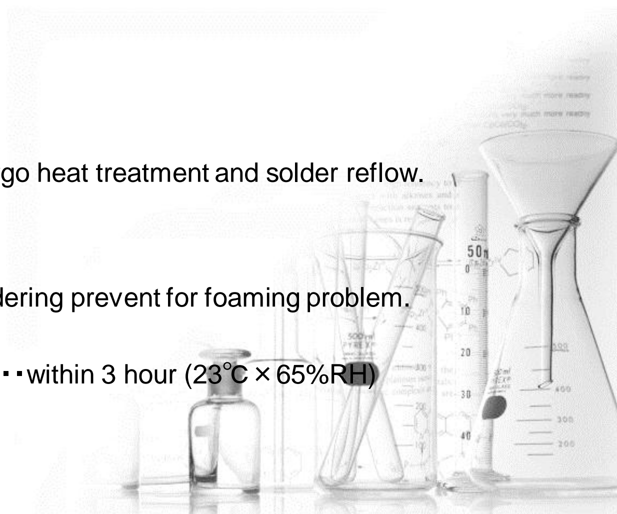
■ Ideal for FPC stiffeners and other materials that undergo heat treatment and solder reflow.

Caution

①Baking process

We will recommend baking process before reflow soldering prevent for foaming problem.
Recommendation condition : 100℃×60 min

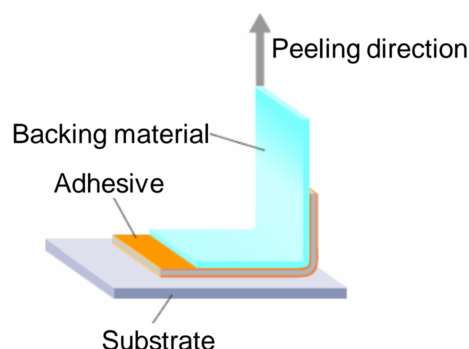
②Substrate leave time before reflow soldering process ･･･within 3 hour (23℃×65%RH)



Technical data

1. Bonding strength on various type of substrate (90° peeling)

<Test piece condition>
Substrate: Glass Epoxy/Polyimide
Tape width: 10mm
Bonding condition: Standard processes
Measuring condition: 23℃±5℃ 60%±20%RH
Peeling speed: 50mm/min
Backing material: CCL (Copper Clad Laminate)
[Left at RT for one hour before measurement]



<90° peeling strength test>

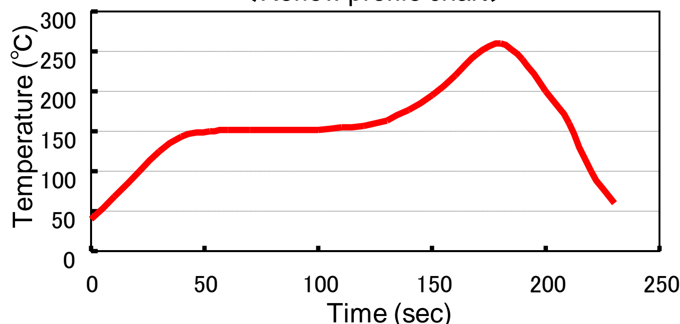
<Results> (N/10mm)

90° peeling strength		D3410	D3411
Long press	CCL/GE	21	17
	CCL/PI	15	13
Quick press and postcure	CCL/GE	20	17
	CCL/PI	20	14

2. Solder reflow process heat resistance

<Test piece condition>
Substrate: Polyimide film/CCL
Bonding condition: standard bonding condition
Solder reflow condition: Top 260℃
(Reference profile)
Measuring condition: 23℃±5℃ 60%±20%RH

<Reflow profile chart>



<Results> ＊Appearance after solder reflow process

Bonding condition	Pre-baking condition*	D3410	D3411
Long press	1/100/-	No change	No change
Vacuum quick press and post cure	1/100/-	No change	No change

※process time (h) / temperature(℃) / humidity(%)

Notes

- Resin flow characteristics in D3410 series is greatly dependent on thickness, size and shapes of stiffeners. Please check the flowing before using. Especially, in the case of using the stiffeners with holes it is necessary to be careful.

Revision in Sep., 2013

Note on the characteristic data given— Data on the characteristics of the products described in this catalog are based on the results of evaluations carried out by the company. This does not guarantee that the characteristics of the product conform with your usage environment. Before use, review the usage conditions based on evaluation data obtained from the equipment and substrates actually used.

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